

致尊敬的顾客

关于产品目录等资料中的旧公司名称

NEC电子公司与株式会社瑞萨科技于2010年4月1日进行业务整合（合并），整合后的新公司暨“瑞萨电子公司”继承两家公司的所有业务。因此，本资料中虽还保留有旧公司名称等标识，但是并不妨碍本资料的有效性，敬请谅解。

瑞萨电子公司网址：<http://www.renesas.com>

2010年4月1日
瑞萨电子公司

【发行】瑞萨电子公司（<http://www.renesas.com>）

【业务咨询】<http://www.renesas.com/inquiry>

Notice

1. All information included in this document is current as of the date this document is issued. Such information, however, is subject to change without any prior notice. Before purchasing or using any Renesas Electronics products listed herein, please confirm the latest product information with a Renesas Electronics sales office. Also, please pay regular and careful attention to additional and different information to be disclosed by Renesas Electronics such as that disclosed through our website.
2. Renesas Electronics does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Renesas Electronics products or technical information described in this document. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
3. You should not alter, modify, copy, or otherwise misappropriate any Renesas Electronics product, whether in whole or in part.
4. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation of these circuits, software, and information in the design of your equipment. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from the use of these circuits, software, or information.
5. When exporting the products or technology described in this document, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations. You should not use Renesas Electronics products or the technology described in this document for any purpose relating to military applications or use by the military, including but not limited to the development of weapons of mass destruction. Renesas Electronics products and technology may not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations.
6. Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.
7. Renesas Electronics products are classified according to the following three quality grades: “Standard”, “High Quality”, and “Specific”. The recommended applications for each Renesas Electronics product depends on the product’s quality grade, as indicated below. You must check the quality grade of each Renesas Electronics product before using it in a particular application. You may not use any Renesas Electronics product for any application categorized as “Specific” without the prior written consent of Renesas Electronics. Further, you may not use any Renesas Electronics product for any application for which it is not intended without the prior written consent of Renesas Electronics. Renesas Electronics shall not be in any way liable for any damages or losses incurred by you or third parties arising from the use of any Renesas Electronics product for an application categorized as “Specific” or for which the product is not intended where you have failed to obtain the prior written consent of Renesas Electronics. The quality grade of each Renesas Electronics product is “Standard” unless otherwise expressly specified in a Renesas Electronics data sheets or data books, etc.
 - “Standard”: Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; and industrial robots.
 - “High Quality”: Transportation equipment (automobiles, trains, ships, etc.); traffic control systems; anti-disaster systems; anti-crime systems; safety equipment; and medical equipment not specifically designed for life support.
 - “Specific”: Aircraft; aerospace equipment; submersible repeaters; nuclear reactor control systems; medical equipment or systems for life support (e.g. artificial life support devices or systems), surgical implantations, or healthcare intervention (e.g. excision, etc.), and any other applications or purposes that pose a direct threat to human life.
8. You should use the Renesas Electronics products described in this document within the range specified by Renesas Electronics, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas Electronics shall have no liability for malfunctions or damages arising out of the use of Renesas Electronics products beyond such specified ranges.
9. Although Renesas Electronics endeavors to improve the quality and reliability of its products, semiconductor products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Further, Renesas Electronics products are not subject to radiation resistance design. Please be sure to implement safety measures to guard them against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas Electronics product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or system manufactured by you.
10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. Please use Renesas Electronics products in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Renesas Electronics assumes no liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
11. This document may not be reproduced or duplicated, in any form, in whole or in part, without prior written consent of Renesas Electronics.
12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products, or if you have any other inquiries.

(Note 1) “Renesas Electronics” as used in this document means Renesas Electronics Corporation and also includes its majority-owned subsidiaries.

(Note 2) “Renesas Electronics product(s)” means any product developed or manufactured by or for Renesas Electronics.

7548/49 群与 7546/47 群

7548/49 群与 7546/47 群的区别

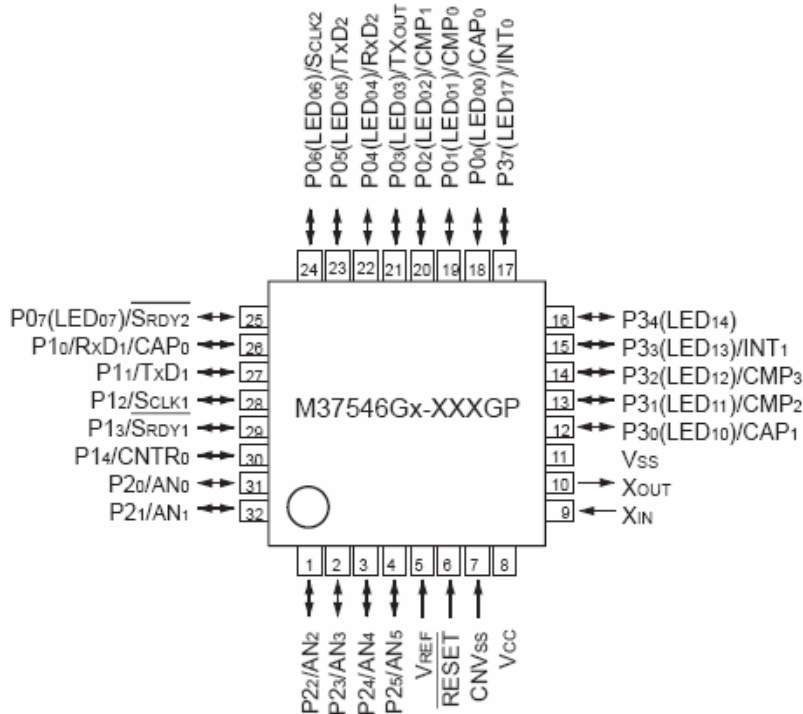
1. 功能上的主要区别

	7546/47群		7548/49 群	
	7546	7547	7548	7549
产品名	M37546G2-XXXGP/HP/SP M37546G2GP/HP/SP M37546G4-XXXGP/HP/SP M37546G4GP/HP/SP	M37547G2-XXXFP M37547G2FP M37547G4-XXXFP M37547G4FP	M37548G3-XXXFP M37548G3FP M37548G2-XXXFP M37548G2FP M37548G1-XXXFP M37548G1FP	M37549G3-XXXFP M37549G3FP M37549G2-XXXFP M37549G2FP M37549G1-XXXFP M37549G1FP
封装	PLQP0032GB-A (32P6U-A) PWQN0036KA-A (36PJW-A) PRDP0032BA-A (32P4B)	PRSP0036GA-A (36P2R-A)	PLSP0020JB-A (20P2F-A)	PRSP0024GA-A (24P2Q-A)
ROM类型 ROM/RAM容量 (字节)	QzROM型: 8K/384 (G2) QzROM型: 16K/512 (G4)		QzROM型: 2K/192 (G1) QzROM型: 4K/256 (G2) QzROM型: 6K/256 (G3)	
可编程I/O端口	25个	29个	15个	19个
LED驱动端口	16个 (输出总峰值电流80mA)		8个	
中断	18个源, 16个向量 (外部中断源6个)		12个源, 12个向量 (外部中断源4个)	
定时器	8位 x 2 (定时器1, X) 16位 x 2 (Timer A, B)		8位 x 2 (定时器1, 2) 16位 x 1 (定时器A)	
输出比较功能	4通道		3通道	
输入捕捉功能	2通道		1通道	
串行接口	8位 x 2 (UART或者时钟同步)		8位 x 1 (UART或者时钟同步)	
A/D转换器	10位分辨率 x 6个通道	10位分辨率 x 8个通道	10位分辨率 x 6个通道	
内部振荡器	2MHz (标准)		内部高速: 4MHz (标准) 内部低速: 250kHz (标准)	

2. 管脚配置的区别

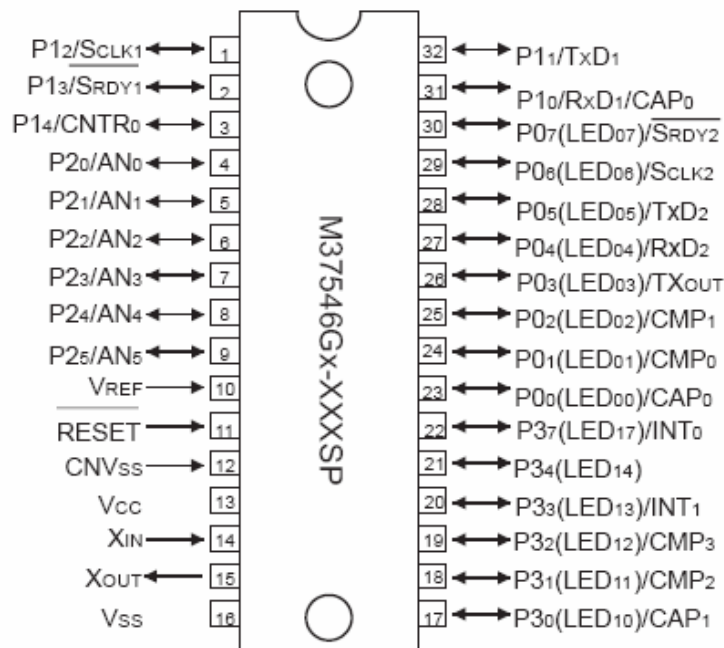
7548/49 群与 7546/47 群的管脚配置和封装类型完全不同，使用中请注意，二者的区别如下：

7546 群管脚连接图（俯视图）



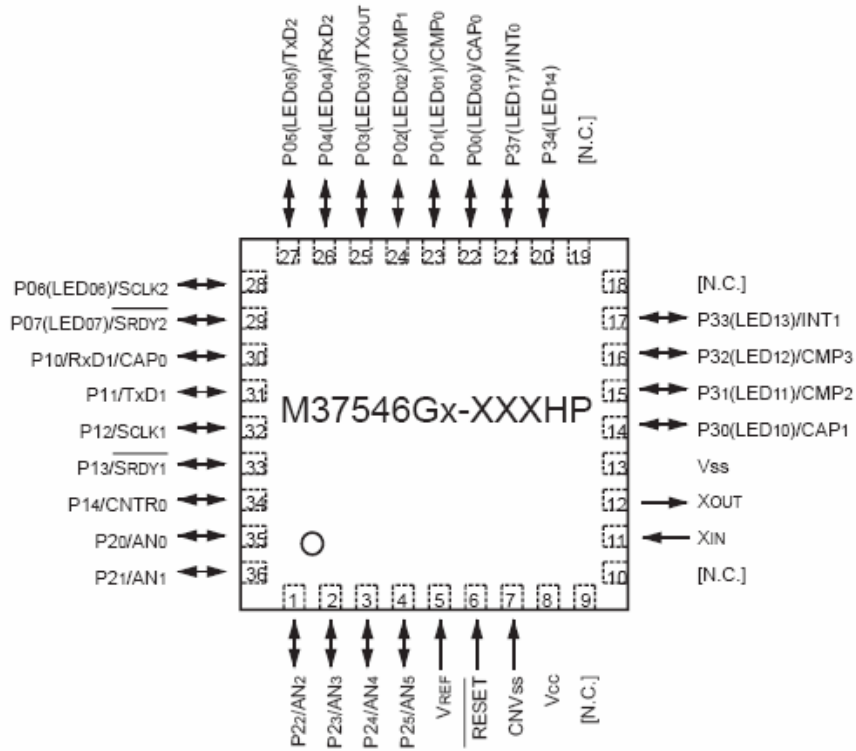
封装：PLQP0032GB-A (32P6U-A)

7546 群管脚连接图（俯视图）



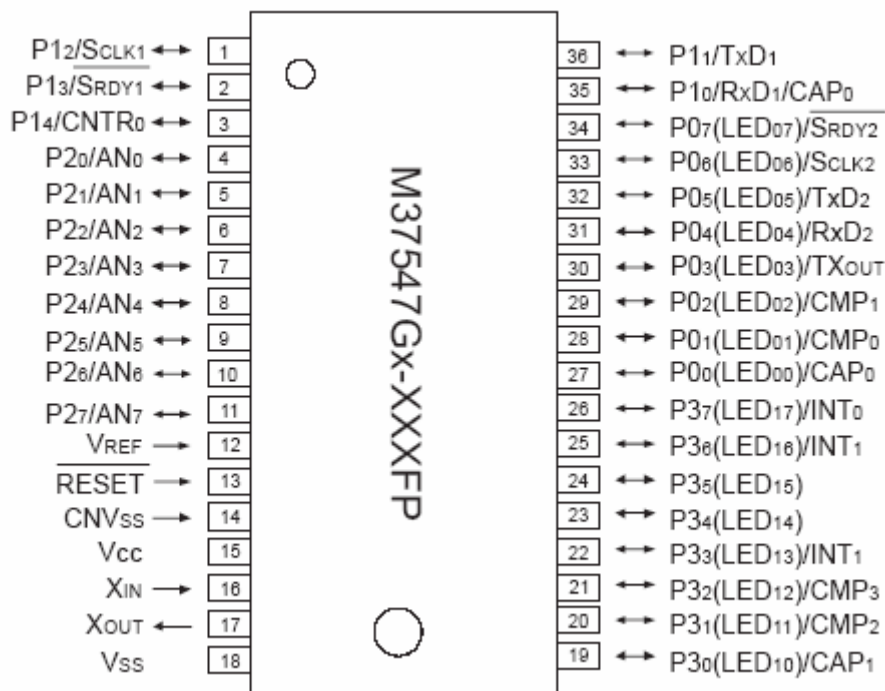
封装：PRDP0032BA-A (32P4B)

7546 群管脚连接图（俯视图）



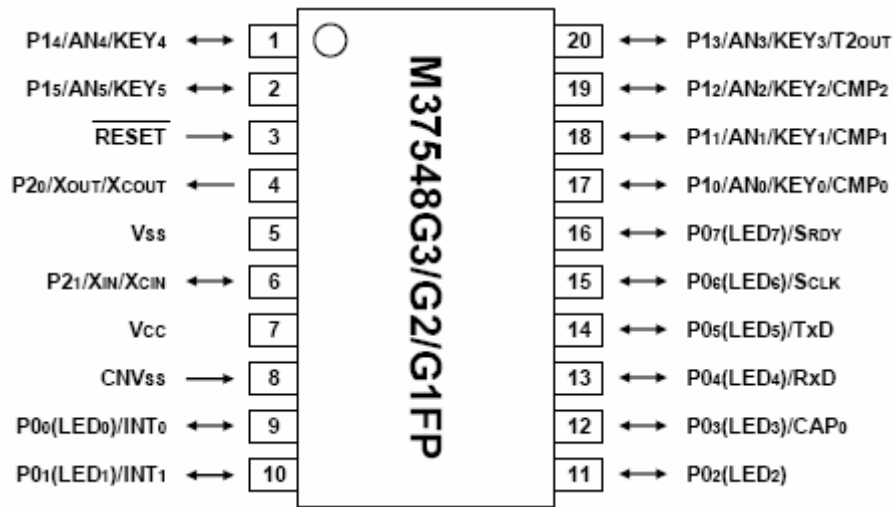
封装: PWQN0036KA-A (36PJW-A)

7547 群管脚连接图（俯视图）



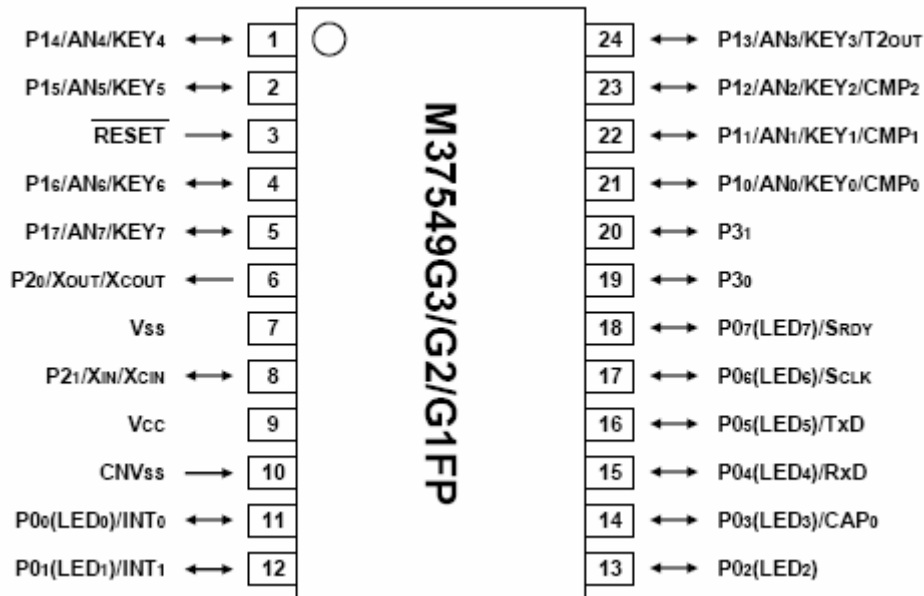
封装: PRSP0036GA-A (36P2R-A)

7548 群管脚连接图（俯视图）



封装: PLSP0020JB-A (20P2F-A)

7549 群管脚连接图（俯视图）



封装: PRSP0024GA-A (24P2Q-A)

3. 控制寄存器的区别

7548/49 群与 7546/47 群的控制寄存器的区别如下:

	7546/47群	7548/49群
0000 ₁₆	端口P0 (P0)	端口P0 (P0)
0001 ₁₆	端口P0方向寄存器 (P0D)	端口P0方向寄存器 (P0D)
0002 ₁₆	端口P1 (P1)	端口P1 (P1)
0003 ₁₆	端口P1方向寄存器 (P1D)	端口P1方向寄存器 (P1D)
0004 ₁₆	端口P2 (P2)	端口P2 (P2)
0005 ₁₆	端口P2方向寄存器 (P2D)	端口P2方向寄存器 (P2D)
0006 ₁₆	端口P3 (P3)	端口P3 (P3) *仅7549
0007 ₁₆	端口P3方向寄存器 (P3D)	端口P3方向寄存器 (P3D)*仅7549
0008 ₁₆	保留区	保留区
0009 ₁₆	保留区	保留区
000A ₁₆	中断源设定寄存器 (INTSET)	保留区
000B ₁₆	中断源识别寄存器 (INTDIS)	保留区
000C ₁₆	捕捉寄存器0 (低位) (CAP0L)	端口P0驱动能力控制寄存器 (DCCR)
000D ₁₆	捕捉寄存器0 (高位) (CAP0H)	端口P0上拉控制寄存器 (PULL0)
000E ₁₆	捕捉寄存器1 (低位) (CAP1L)	端口P1上拉控制寄存器 (PULL1)
000F ₁₆	捕捉寄存器1 (高位) (CAP1H)	键输入选择寄存器 (KEYS)
0010 ₁₆	比较寄存器 (低位) (CMPL)	捕捉/比较寄存器 (低位) (CRAL)
0011 ₁₆	比较寄存器 (高位) (CMPH)	捕捉/比较寄存器 (高位) (CRAH)
0012 ₁₆	捕捉/比较寄存器R/W指针 (CCRP)	捕捉/比较寄存器R/W指针 (CCRP)
0013 ₁₆	捕捉软件触发寄存器 (CSTR)	比较输出模式寄存器 (CMOM)
0014 ₁₆	比较设定值再装入寄存器 (CMPR)	定时器A (低位) (TAL)
0015 ₁₆	端口POP3驱动能力控制寄存器 (DCCR)	定时器A (高位) (TAH)
0016 ₁₆	上拉控制寄存器 (PULL)	保留区
0017 ₁₆	端口P1P3控制寄存器 (P1P3C)	保留区
0018 ₁₆	发送1/接收1缓冲寄存器1 (TB1/RB1)	发送/接收缓冲寄存器 (TB/RB)
0019 ₁₆	串行I/O1状态寄存器 (SIO1STS)	串行I/O状态寄存器 (SIOSTS)
001A ₁₆	串行I/O1控制寄存器 (SIO1CON)	串行I/O控制寄存器 (SIOCON)
001B ₁₆	UART1控制寄存器 (UART1CON)	UART控制寄存器 (UARTCON)
001C ₁₆	波特率发生器1 (BRG1)	波特率发生器 (BRG)
001D ₁₆	定时器A, B模式寄存器 (TABM)	保留区
001E ₁₆	捕捉/比较端口寄存器 (CCPR)	保留区
001F ₁₆	捕捉/比较定时器源选择寄存器 (TMSR)	保留区
0020 ₁₆	捕捉模式寄存器 (CAPM)	保留区
0021 ₁₆	比较输出模式寄存器 (CMOM)	保留区
0022 ₁₆	捕捉/比较状态寄存器 (CCSR)	保留区
0023 ₁₆	比较中断源设定寄存器 (CISR)	保留区
0024 ₁₆	定时器A (低位) (TAL)	保留区
0025 ₁₆	定时器A (高位) (TAH)	保留区
0026 ₁₆	定时器B (低位) (TBL)	保留区
0027 ₁₆	定时器B (高位) (TBH)	保留区
0028 ₁₆	预定标器1 (PRE1)	预定标器12 (PRE12)
0029 ₁₆	定时器1 (T1)	定时器1 (T1)
002A ₁₆	定时器计数源设定寄存器 (TCSS)	定时器2 (T2)

002B ₁₆	定时器X模式寄存器 (TXM)	定时器模式寄存器 (TM)
002C ₁₆	预定标器X (PREX)	定时器计数源设定寄存器 (TCSS)
002D ₁₆	定时器X (TX)	比较设定值再装入寄存器 (CMPR)
002E ₁₆	发送2/接收2缓冲寄存器2 (TB2/RB2)	捕捉/比较端口寄存器 (CCPR)
002F ₁₆	串行I/O2状态寄存器 (SIO2STS)	捕捉/比较状态寄存器 (CCSR)
0030 ₁₆	串行I/O2控制寄存器 (SIO2CON)	比较中断源设定寄存器 (CISR)
0031 ₁₆	UART2控制寄存器 (UART2CON)	捕捉软件触发寄存器 (CSTR)
0032 ₁₆	波特率发生器2 (BRG2)	捕捉模式寄存器 (CAPM)
0033 ₁₆	保留区	保留区
0034 ₁₆	A/D控制寄存器 (ADCON)	A/D控制寄存器 (ADCON)
0035 ₁₆	A/D转换寄存器(低位) (ADL)	A/D转换寄存器(低位) (ADL)
0036 ₁₆	A/D转换寄存器(高位) (ADH)	A/D转换寄存器(高位) (ADH)
0037 ₁₆	内部振荡器分频比选择寄存器 (RODR)	时钟模式寄存器 (CLKM)
0038 ₁₆	MISRG	振荡器停止检测寄存器 (CLKSTP)
0039 ₁₆	监视定时器控制寄存器 (WDTCON)	监视定时器控制寄存器 (WDTCON)
003A ₁₆	中断边沿选择寄存器 (INTEDGE)	中断边沿选择寄存器 (INTEDGE)
003B ₁₆	CPU模式寄存器 (CPUM)	CPU模式寄存器 (CPUM)
003C ₁₆	中断请求寄存器1 (IREQ1)	中断请求寄存器1 (IREQ1)
003D ₁₆	中断请求寄存器2 (IREQ2)	中断请求寄存器2 (IREQ2)
003E ₁₆	中断控制寄存器1 (ICON1)	中断控制寄存器1 (ICON1)
003F ₁₆	中断控制寄存器2 (ICON2)	中断控制寄存器2 (ICON2)

注: 不要对SFR保留区进行存取。

- : 7548/49群增加的SFR
- : 7548/49群有改变的SFR
- : 仅7546/47群有

4. 中断向量的区别

7548/49 群与 7546/47 群在中断源与向量地址上有较大不同，与此相关的中断请求寄存器和中断控制控制寄存器也有相应变化，使用时请参考相关寄存器结构说明。

7548/49群与7546/47群中断向量的不同处 =

向量地址		优先级	7546/47群中断源	7548/49群中断源
高位	低位			
FFFD ₁₆	FFFC ₁₆	1	复位	复位
FFFB ₁₆	FFFA ₁₆	2	串行I/O1接收	串行I/O接收
FFF9 ₁₆	FFF8 ₁₆	3	串行I/O1发送	串行I/O发送
FFF7 ₁₆	FFF6 ₁₆	4	串行I/O2接收	INT ₀
FFF5 ₁₆	FFF4 ₁₆	5	串行I/O2发送	INT ₁
FFF3 ₁₆	FFF2 ₁₆	6	INT ₀	键唤醒
FFF1 ₁₆	FFF0 ₁₆	7	INT ₁	捕捉
FFEF ₁₆	FFEE ₁₆	8	键唤醒 / UART1 总线冲突检测	比较
FFED ₁₆	FFEC ₁₆	9	CNTR ₀	定时器A
FFEB ₁₆	FFEA ₁₆	10	捕捉0	定时器2
FFE9 ₁₆	FFE8 ₁₆	11	捕捉1	A/D转换

(接上表)

FFE7 ₁₆	FFE6 ₁₆	12	比较	定时器1
FFE5 ₁₆	FFE4 ₁₆	13	定时器X	保留区
FFE3 ₁₆	FFE2 ₁₆	14	定时器A	保留区
FFE1 ₁₆	FFE0 ₁₆	15	定时器B	保留区
FFDF ₁₆	FFDE ₁₆	16	A/D转换 / 定时器1	保留区
FFDD ₁₆	FFDC ₁₆	17	BRK指令	BRK指令

5. 时钟发生电路的区别

7548/49 群与 7546/47 群的时钟产生电路的不同如下图所示。

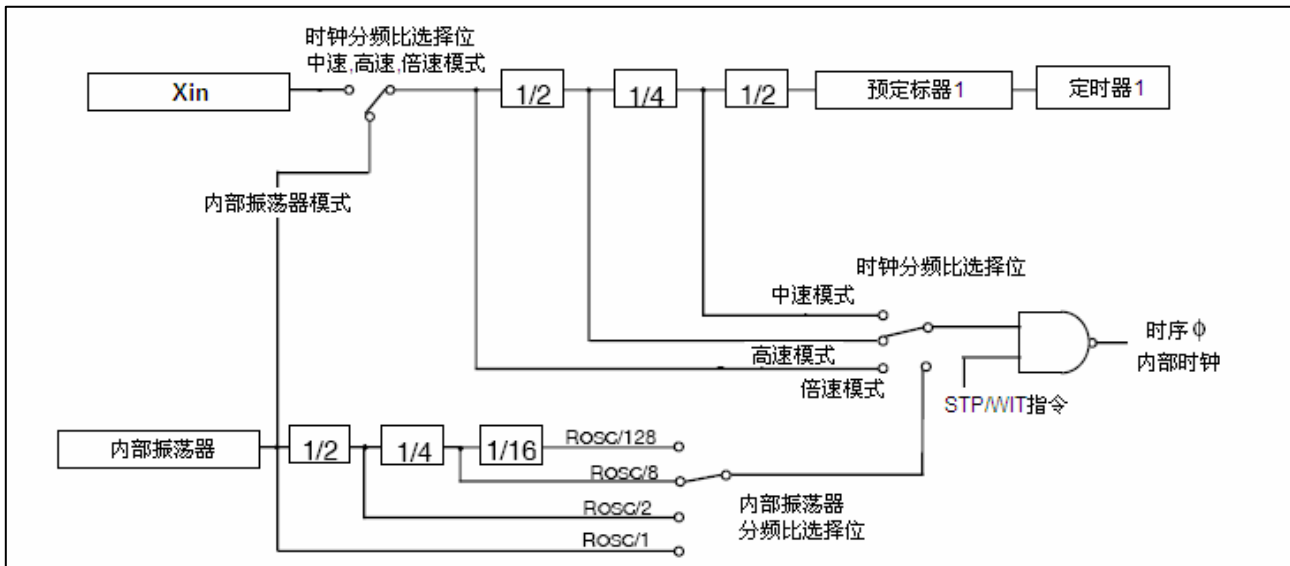


图 1. 7546/47 群时钟发生电路框图

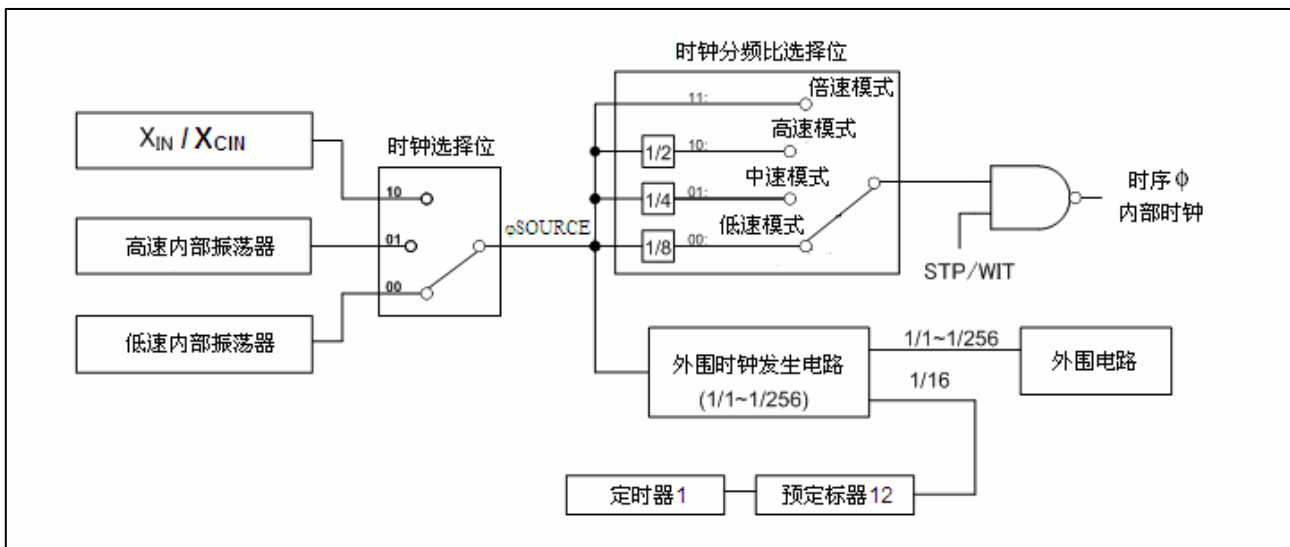


图 2. 7548/49 群时钟发生电路框图

6. 定时器功能的区别

7548/49 群与 7546/47 群相比，在定时器功能上有较大变化，简化了定时器 2 的部分功能，二者区别见下表：

7546/47 群定时器功能		7548/49 群定时器功能	
8位定时器1 (预定标器1)	计数源：f(XIN)/16, 或内部振荡器16分频输出 (由CPUM寄存器设定)	8位定时器1 (预定标器12)	计数源：f(ϕ SOURCE)/16, 或f(XCIN): 32kHz晶振 (由CLKM和TCSS寄存器设定)
8位定时器X (预定标器X)	计数源：f(XIN)/16, f(XIN)/2, f(XIN) (由TCSS寄存器设定)	8位定时器2 (预定标器12)	计数源：f(ϕ SOURCE)/16, f(ϕ SOURCE)/256, 预定标器12输出, 定时器A下溢 (由CLKM和TCSS寄存器设定)
	定时器X有以下4种模式： (由TXM寄存器设定) (1) 定时器模式 (2) 脉冲输出模式 (3) 事件计数器模式 (4) 脉冲宽度测定模式		定时器2有以下2种模式： (由TM寄存器设定) (1) 定时器模式 (2) 脉冲输出模式
16位定时器A/B	计数源：f(XIN)/16, f(XIN)/2, f(XIN)/32, f(XIN)/64, f(XIN)/128, f(XIN)/256 或者 内部振荡器输出 (仅定时器A), 定时器A下溢 (仅定时器B) (由TCSS寄存器设定)	16位定时器A	计数源：f(ϕ SOURCE)/16, f(ϕ SOURCE)/2, f(ϕ SOURCE)/32, f(ϕ SOURCE)/64, f(ϕ SOURCE)/128, f(ϕ SOURCE)/256, f(LSOCO), f(XCIN) (由CLKM和TCSS寄存器设定)
	定时器A/B有以下3种模式： (1) 定时器模式 (2) 输出比较 (有正常输出和调制输出两种模式) (3) 输入捕捉模式		定时器A有3种模式： (1) 定时器模式 (2) 输出比较 (仅有正常输出模式) (3) 输入捕捉模式

7. 参考文献

硬件手册:

7546 群数据手册

7547 群数据手册

7548 群数据手册

7549 群数据手册

(最新版本请从瑞萨科技网页上取得)

技术信息/技术更新

(最新版本请从瑞萨科技网页上取得)

公司主页和咨询窗口

瑞萨科技公司主页

<http://www.cn.renesas.com>

咨询

<http://www.cn.renesas.com/inquiry>
contact.china@renesas.com

修订记录

Rev.	发行日	修订内容	
		页	要点
1.00	2006.08.23	—	初版发行
2.00	2008.03.17	1	修改页眉
			修改表中 7548/49 群中断内容
		7	修改图 2 内容（增加 XCIN 时钟源；系统时钟 → Φ_{source} ；删去文字“系统”和“CPU”）
		8	修改表中 7548/49 群时钟源内容
		9	更新咨询邮箱地址

Notes regarding these materials

1. This document is provided for reference purposes only so that Renesas customers may select the appropriate Renesas products for their use. Renesas neither makes warranties or representations with respect to the accuracy or completeness of the information contained in this document nor grants any license to any intellectual property rights or any other rights of Renesas or any third party with respect to the information in this document.
2. Renesas shall have no liability for damages or infringement of any intellectual property or other rights arising out of the use of any information in this document, including, but not limited to, product data, diagrams, charts, programs, algorithms, and application circuit examples.
3. You should not use the products or the technology described in this document for the purpose of military applications such as the development of weapons of mass destruction or for the purpose of any other military use. When exporting the products or technology described herein, you should follow the applicable export control laws and regulations, and procedures required by such laws and regulations.
4. All information included in this document such as product data, diagrams, charts, programs, algorithms, and application circuit examples, is current as of the date this document is issued. Such information, however, is subject to change without any prior notice. Before purchasing or using any Renesas products listed in this document, please confirm the latest product information with a Renesas sales office. Also, please pay regular and careful attention to additional and different information to be disclosed by Renesas such as that disclosed through our website. (<http://www.renesas.com>)
5. Renesas has used reasonable care in compiling the information included in this document, but Renesas assumes no liability whatsoever for any damages incurred as a result of errors or omissions in the information included in this document.
6. When using or otherwise relying on the information in this document, you should evaluate the information in light of the total system before deciding about the applicability of such information to the intended application. Renesas makes no representations, warranties or guaranties regarding the suitability of its products for any particular application and specifically disclaims any liability arising out of the application and use of the information in this document or Renesas products.
7. With the exception of products specified by Renesas as suitable for automobile applications, Renesas products are not designed, manufactured or tested for applications or otherwise in systems the failure or malfunction of which may cause a direct threat to human life or create a risk of human injury or which require especially high quality and reliability such as safety systems, or equipment or systems for transportation and traffic, healthcare, combustion control, aerospace and aeronautics, nuclear power, or undersea communication transmission. If you are considering the use of our products for such purposes, please contact a Renesas sales office beforehand. Renesas shall have no liability for damages arising out of the uses set forth above.
8. Notwithstanding the preceding paragraph, you should not use Renesas products for the purposes listed below:
 - (1) artificial life support devices or systems
 - (2) surgical implantations
 - (3) healthcare intervention (e.g., excision, administration of medication, etc.)
 - (4) any other purposes that pose a direct threat to human life

Renesas shall have no liability for damages arising out of the uses set forth in the above and purchasers who elect to use Renesas products in any of the foregoing applications shall indemnify and hold harmless Renesas Technology Corp., its affiliated companies and their officers, directors, and employees against any and all damages arising out of such applications.
9. You should use the products described herein within the range specified by Renesas, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas shall have no liability for malfunctions or damages arising out of the use of Renesas products beyond such specified ranges.
10. Although Renesas endeavors to improve the quality and reliability of its products, IC products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Please be sure to implement safety measures to guard against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other applicable measures. Among others, since the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or system manufactured by you.
11. In case Renesas products listed in this document are detached from the products to which the Renesas products are attached or affixed, the risk of accident such as swallowing by infants and small children is very high. You should implement safety measures so that Renesas products may not be easily detached from your products. Renesas shall have no liability for damages arising out of such detachment.
12. This document may not be reproduced or duplicated, in any form, in whole or in part, without prior written approval from Renesas.
13. Please contact a Renesas sales office if you have any questions regarding the information contained in this document, Renesas semiconductor products, or if you have any other inquiries.

注意

本文只是参考译文，前页所载英文版“Cautions”具有正式效力。

关于利用本资料时的注意事项

1. 本资料是为了让用户根据用途选择合适的本公司产品的参考资料，对于本资料中所记载的技术信息，并非意味着对本公司或者第三者的知识产权及其他权利做出保证或对实施权力进行的承诺。
2. 对于因使用本资料所记载的产品数据、图、表、程序、算法及其他应用电路例而引起的损害或者对第三者的知识产权及其他权利造成侵犯，本公司不承担任何责任。
3. 不能将本资料所记载的产品和技术用于大规模破坏性武器的开发等目的、军事目的或其他的军需用途方面。另外，在出口时必须遵守日本的《外汇及外国贸易法》及其他出口的相关法令并履行这些法令中规定的必要手续。
4. 本资料所记载的产品数据、图、表、程序、算法以及其他应用电路例等所有信息均为本资料发行时的内容，本公司有可能在未做事先通知的情况下，对本资料所记载的产品或者产品规格进行更改。所以在购买和使用本公司的半导体产品之前，请事先向本公司的营业窗口确认最新的信息并经常留意本公司通过公司主页（<http://www.renesas.com>）等公开的最新信息。
5. 对于本资料中所记载的信息，制作时我们尽力保证出版时的精确性，但不承担因本资料的叙述不当而使顾客遭受损失等的任何相关责任。
6. 在使用本资料所记载的产品数据、图、表等所示的技术内容、程序、算法及其他应用电路例时，不仅要对所使用的技术信息进行单独评价，还要对整个系统进行充分的评价。请顾客自行负责，进行是否适用的判断。本公司对于是否适用不负任何责任。
7. 本资料中所记载的产品并非针对万一出现故障或是错误运行就会威胁到人的生命或给人体带来危害的机器、系统（如各种安全装置或者运输交通用的、医疗、燃烧控制、航天器械、核能、海底中继用的机器和系统等）而设计和制造的，特别是对于品质和可靠性要求极高的机器和系统等（将本公司指定用于汽车方面的产品用于汽车时除外）。如果要用于上述的目的，请务必事先向本公司的营业窗口咨询。另外，对于用于上述目的而造成的损失等，本公司概不负责。
8. 除上述第7项内容外，不能将本资料中记载的产品用于以下用途。如果用于以下用途而造成的损失，本公司概不负责。
 - 1) 生命维持装置。
 - 2) 植埋于人体使用的装置。
 - 3) 用于治疗（切除患部、给药等）的装置。
 - 4) 其他直接影响到人的生命的装置。
9. 在使用本资料所记载的产品时，对于最大额定值、工作电源电压的范围、放热特性、安装条件及其他条件请在本公司规定的保证范围内使用。如果超出了本公司规定的保证范围使用时，对于由此而造成的故障和出现的事故，本公司将不承担任何责任。
10. 本公司一直致力于提高产品的质量和可靠性，但一般来说，半导体产品总会以一定的概率发生故障、或者由于使用条件不同而出现错误运行等。为了避免因本公司的产品发生故障或者错误运行而导致人身事故和火灾或造成社会性的损失，希望客户能自行负责进行冗余设计、采取延烧对策及进行防止错误运行等的安全设计（包括硬件和软件两方面的设计）以及老化处理等，这是作为机器和系统的出厂保证。特别是单片机的软件，由于单独进行验证很困难，所以要求在顾客制造的最终的机器及系统上进行安全检验工作。
11. 如果把本资料所记载的产品从其载体设备上卸下，有可能造成婴儿误吞的危险。顾客在将本公司产品安装到顾客的设备上时，请顾客自行负责将本公司产品设置为不容易剥落的安全设计。如果从顾客的设备上剥落而造成事故时，本公司将不承担任何责任。
12. 在未得到本公司的事先书面认可时，不可将本资料的一部分或者全部转载或者复制。
13. 如果需要了解关于本资料的详细内容，或者有其他关心的问题，请向本公司的营业窗口咨询。

© 2008. Renesas Technology Corp., All rights reserved.